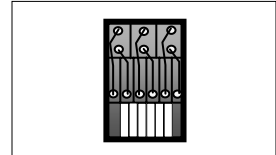


Earl J. Lum
+1-650-430-2221
elum@ejlwireless.com



Nokia W-CDMA 2100MHz Power Amplifier Model 468277A WPAB

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